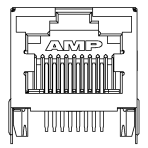
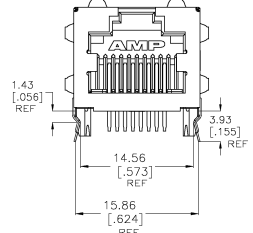


406541-1, -3, & -6
 1-406541-1, 1--3, & 1--6

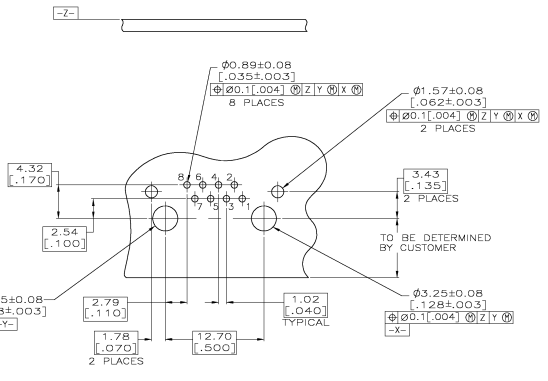
406541-4
 1-406541-4
 WITHOUT LOWER
 RIGHT PANEL GROUND



406541-5
 1-406541-5
 WITHOUT PANEL GROUNDS



1-406541-7



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

- △ MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE BRIGHT (SEE P/N TABLE) IN SOLDER AREA, 1.27µm [0.00050] MINIMUM GOLD IN LOCALIZED PLATE AREA, ENTIRE TERMINAL PLATED WITH 1.27µm [0.00050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPARED WITH 1.27µm[0.00050] MINIMUM NICKEL WITH 2.03µm[0.00080] MINIMUM (SEE P/N TABLE) POST DIPPED ON PCB GROUND TABS.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- △ ON 406541-4 & 1-406541-4 LOWER RIGHT HAND PANEL GROUND TAB IS NOT PRESENT.
- △ MANUFACTURING DATE CODE: BLACK INK STAMP, LOCATED APPROX. AS SHOWN. FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR. NEXT 2 DIGITS = MANUFACTURING WORK WEEK. LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1.

SnAgCu	TIN	6	2.54 [.100]	1-406541-7
		6	3.56 [.140]	1-406541-6
		0	2.54 [.100]	1-406541-5
		5	2.54 [.100]	1-406541-4
		6	2.00 [.079]	1-406541-3
TIN-LEAD	TIN-LEAD	6	2.54 [.100]	1-406541-1
		6	3.56 [.140]	406541-6
		0	2.54 [.100]	406541-5
		5	2.54 [.100]	406541-4
		6	2.00 [.079]	406541-3
6	2.54 [.100]	406541-1		

SHIELD SOLDER TAIL PLATING		△	TERMINAL PLATING	△	PANEL GROUNDS	△	DIM. A	△	PART NUMBER
THIS DRAWING IS A CONTROLLED DOCUMENT									
REVISED	DATE	BY	DESCRIPTION	REVISED	DATE	BY	DESCRIPTION	REVISED	DATE
1	00779	A	INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, PANEL GROUND	1	00779	A	INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, PANEL GROUND	1	00779
CUSTOMER DRAWING		DATE		REVISED		DATE		REVISED	
1		4-1		1		4-1		1	